

Silicon Carbide (SiC) JFET – EliteSiC, Power N-Channel, TO247-3, 1200 V, 35 mohm

UJ3N120035K3S

Description

onsemi offers the high–performance G3 SiC normally-on JFET transistors. This series exhibits ultra-low on resistance ($R_{DS(ON)}$) and gate charge (Q_G) allowing for low conduction and switching loss. The device normally-on characteristics with low $R_{DS(ON)}$ at $V_{GS}=0$ V is also ideal for current protection circuits without the need for active control, as well as for cascode operation.

Features

- Typical On-resistance $R_{DS(on), typ}$ of 35 m Ω
- Voltage Controlled
- Maximum Operating Temperature of 175 °C
- Extremely Fast Switching not Dependent on Temperature
- Low Gate Charge
- Low Intrinsic Capacitance
- This Device is Pb-Free, Halogen Free and is ROHS Compliant

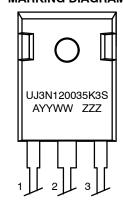
Typical Applications

- Over Current Protection Circuits
- DC-AC Inverters
- Switch Mode Power Supplies
- Power Factor Correction Modules
- Motor Drives
- Induction Heating



TO247-3 CASE 340AK

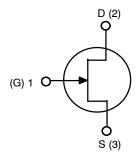
MARKING DIAGRAM



UJ3N120035K3S = Specific Device Code

A = Assembly Location

PIN CONNECTIONS



ORDERING INFORMATION

See detailed ordering and shipping information on page 7 of this data sheet.

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MAXIMUM RATINGS

Parameter	Symbol	Test Conditions	Value	Unit
Drain-source Voltage	V _{DS}		1200	V
Gate-source Voltage	V_{GS}	DC	-20 to +3	V
		AC (Note 1)	-20 to +20	
Continuous Drain Current (Note 2)	I _D	T _C = 25 °C	63	Α
		T _C = 100 °C	46	
Pulsed Drain Current (Note 3)	I _{DM}	T _C = 25 °C	185	Α
Power Dissipation	P _{tot}	T _C = 25 °C	429	W
Maximum Junction Temperature	$T_{J,max}$		175	°C
Operating and Storage Temperature	T _J , T _{STG}		-55 to 175	°C
Max. Lead Temperature for Soldering, 1/8" from Case for 5 Seconds	TL		250	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. +20 V AC rating applies for turn-on pulses <200 ns applied with external R_G > 1 Ω.

2. Limited by T_{J, max}

3. Pulse width t_p limited by T_{J, max}

THERMAL CHARACTERISTICS

			Value			
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$		-	0.27	0.35	°C/W

ELECTRICAL CHARACTERISTICS (T_J = $\pm 25~^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
TYPICAL PERFORMANCE - STATIC						
Drain-source Breakdown Voltage	BV _{DS}	$V_{GS} = -20 \text{ V}, I_D = 1 \text{ mA}$	1200	-	-	V
Total Drain Leakage Current	I _D	$V_{DS} = 1200 \text{ V}, V_{GS} = -20 \text{ V},$ $T_{J} = 25 ^{\circ}\text{C}$	-	10	60	μΑ
		V _{DS} = 1200 V, V _{GS} = -20 V, T _J = 175°C	-	35	-	
Total Gate Leakage Current	I _G	V _{GS} = −20 V, T _J = 25 °C	_	12	100	μΑ
		V _{GS} = -20 V, T _J = 175 °C	-	50	-	
Drain-source On-resistance	R _{DS(on)}	$V_{GS} = 2 \text{ V}, I_D = 20 \text{ A}, T_J = 25^{\circ}\text{C}$	-	31	-	mΩ
		$V_{GS} = 0 \text{ V}, I_D = 20 \text{ A}, T_J = 25^{\circ}\text{C}$	-	35	45	
		V _{GS} = 2 V, I _D = 20 A, T _J = 175°C	-	68	-	
		V _{GS} = 0 V, I _D = 20 A, T _J = 175°C	-	76	-	
Gate Threshold Voltage	$V_{G(th)}$	$V_{DS} = 5 \text{ V}, I_{D} = 70 \text{ mA}$	-14	-11.5	-6	V
Gate Resistance	R_{G}	f = 1 MHz, open drain	-	2.4	-	Ω

ELECTRICAL CHARACTERISTICS (T_J = +25 $^{\circ}C$ unless otherwise specified) (continued)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit	
TYPICAL PERFORMANCE - DYNAMIC							
Input Capacitance	C _{iss}	V _{DS} = 100 V, V _{GS} = -20 V,	_	2145	-	pF	
Output Capacitance	C _{oss}	f = 100 kHz	-	180	-		
Reverse Transfer Capacitance	C _{rss}		-	172	-		
Effective Output Capacitance, Energy Related	C _{oss(er)}	$V_{DS} = 0 \text{ V to } 800 \text{ V}, V_{GS} = -20 \text{ V}$	-	105	-	pF	
Total Gate Charge	Q_{G}	V _{DS} = 800 V, I _D = 40 A,	-	235	-	nC	
Gate-drain Charge	Q_{GD}	V _{GS} = -18 V to 0 V	-	130	-		
Gate-source Charge	Q_{GS}		-	25	-		
Turn-on Delay Time	t _{d(on)}	$V_{DS} = 800 \text{ V}, I_D = 40 \text{ A},$	-	25	-	ns	
Rise Time	t _r	Gate Driver = -18 V to 0 V, $R_{G, EXT} = 1 \Omega$, Inductive Load, FWD: UJ3D1220KSD $T_{J} = 25 ^{\circ}\text{C}$	-	37	-		
Turn-off Delay Time	t _{d(off)}		-	48	-		
Fall Time	t _f		-	39	-		
Turn-on Energy	E _{ON}		1	935	ı	μJ	
Turn-off Energy	E _{OFF}		-	828	-		
Total Switching Energy	E _{TOTAL}		-	1763	-		
Turn-on Delay Time	t _{d(on)}	$V_{DS} = 800 \text{ V}, I_D = 40 \text{ A},$	-	24	-	ns	
Rise Time	t _r	Gate Driver = -18 V to 0 V , $R_{G, EXT} = 1 \Omega$,	-	35	-		
Turn-off Delay Time	t _{d(off)}	Inductive Load, FWD: UJ3D1220KSD	-	43	-		
Fall Time	t _f	$T_J = 150 ^{\circ}\text{C}$	-	37	-		
Turn-on Energy	E _{ON}		_	880	-	μJ	
Turn-off Energy	E _{OFF}		_	800	-		
Total Switching Energy	E _{TOTAL}		-	1680	-		

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL PERFORMANCE DIAGRAMS

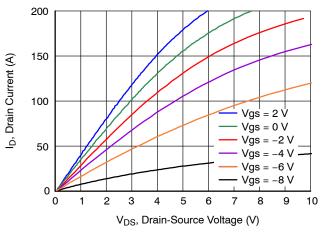


Figure 1. Typical Output Characteristics at $T_J = -55$ °C

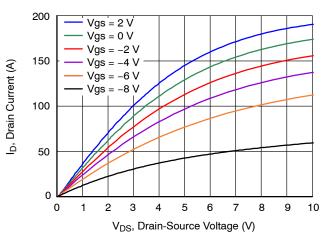


Figure 2. Typical Output Characteristics at $T_J = 25$ °C

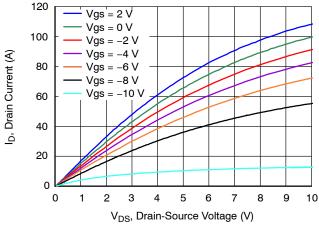


Figure 3. Typical Output Characteristics at $T_J = 175$ °C

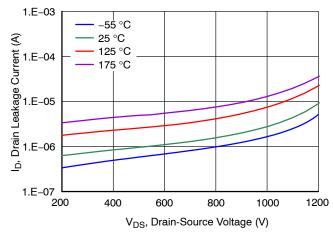


Figure 4. Typical Drain-Source Leakage at V_{GS} = -20 V

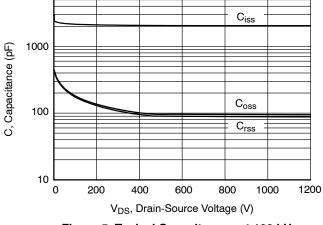


Figure 5. Typical Capacitances at 100 kHz and V_{GS} = -20 V

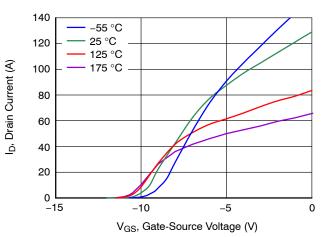


Figure 6. Typical Transfer Characteristics at $V_{DS} = 5 \text{ V}$

TYPICAL PERFORMANCE DIAGRAMS (continued)

Eoss (MJ)

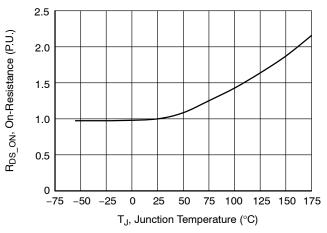


Figure 7. Normalized On-Resistance vs. Temperature at V_{GS} = 0 V and I_{D} = 20 A

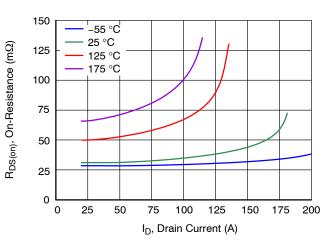


Figure 8. Typical Drain-Source On-Resistance at $V_{GS} = 0 \text{ V}$

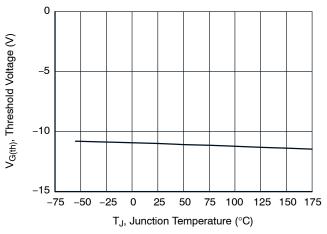


Figure 9. Threshold Voltage vs. T_J at V_{DS} = 5 V and I_D = 70 mA

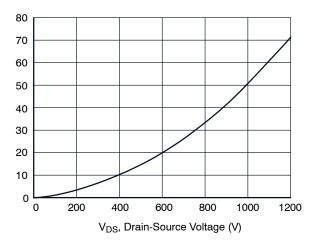


Figure 10. Typical Stored Energy in C_{oss} at $V_{GS} = -20 \text{ V}$

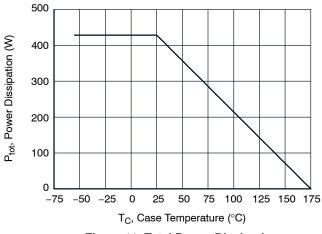


Figure 11. Total Power Dissipation

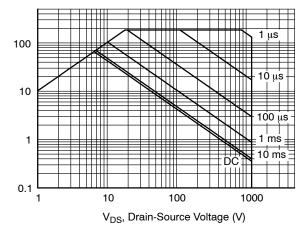


Figure 12. Safe Operation Area T_C = 25 °C, Parameter t_p

_D, Drain Current (A)

TYPICAL PERFORMANCE DIAGRAMS (continued)

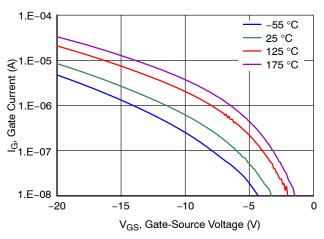


Figure 13. Typical Gate Leakage Current at V_{DS} = 0 V

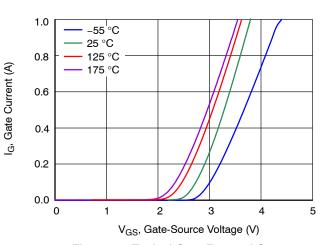


Figure 14. Typical Gate Forward Current at V_{DS} = 0 V

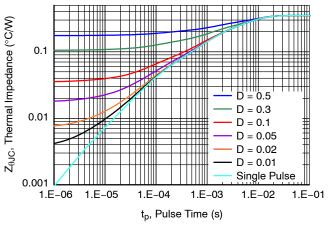


Figure 15. Maximum Transient Thermal Impedance

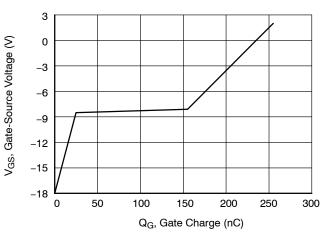


Figure 16. Typical Gate Charge at V_{DS} = 800 V and I_D = 40 A

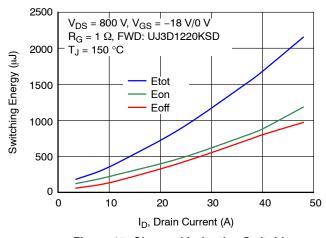


Figure 17. Clamped Inductive Switching Energy vs. Drain Current at T_J = 150 °C

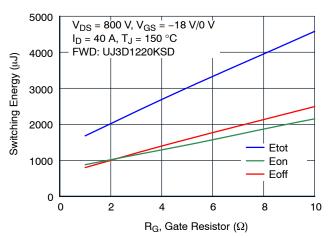


Figure 18. Clamped Inductive Switching Energy vs. Gate Resistor R_G

TYPICAL PERFORMANCE DIAGRAMS (continued)

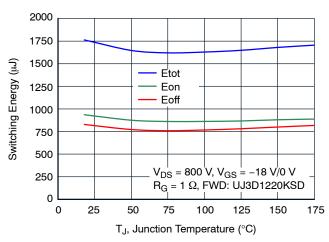


Figure 19. Clamped Inductive Switching Energy vs. Junction Temperature at I_D = 40 A

ORDERING INFORMATION

Part Number	Marking	Package	Shipping
UJ3N120035K3S	UJ3N120035K3S	TO247-3 (Pb-Free, Halogen Free)	600 Units / Tube

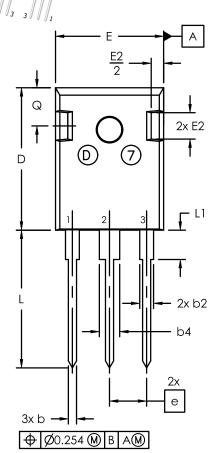
REVISION HISTORY

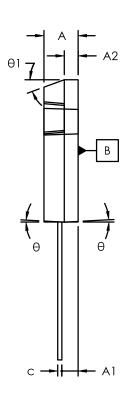
Revision	Description of Changes	Date
С	Acquired the original Qorvo JFET Division Data Sheet and updated the main document title to comply with onsemi standards for SiC products.	3/21/2025
3	Converted the Data Sheet to onsemi format.	5/13/2025

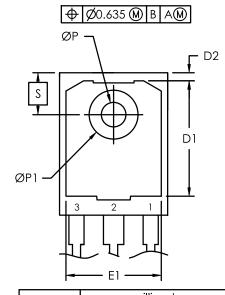




DATE 14 APR 2025







SYM	millimeters					
317/1	MIN	NOM	MAX			
Α	4.70	5.03	5.31			
A1	2.21	2.40	2.59			
A2	1.50	2.03	2.49			
b	0.99	1.20	1.40			
b2	1.65	2.03	2.39			
b4	2.59	3.00	3.43			
c D	0.38	0.60	0.89			
D	20.70	20.96	21.46			
D1	13.08	ı	ı			
D2	0.51	1.19	1.35			
Е	15.49	15.90	16.26			
е		5.44 BSC				
E1	13.00	13.30	13.60			
E2	3.43	3.89	5.20			
L	19.62	20.27	20.32			
L1	1	1	4.50			
ØP	3.40	3.60	3.80			
ØP1	7.06	7.19	7.39			
Q	5.38	5.62	6.20			
S	6.15 BSC					
θ	3°					
θ1	20°					
θ2	10°					

θ2

NOTE:

- 1. Dimensioning and tolerancing as per ASME Y14.5 2018
- 2. Controlling dimension: millimeters
- 3. Package Outline in compliance with JEDEC standard var. AD.
- 4. Dimensions D & E does not include mold flash.
- 5. ØP to have max draft angle of 1.7° to the top with max. hole diameter of 3.91mm.

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DESCRIPTION:	TO247-3 15.90x20.96x5.03, 5.44P		PAGE 1 OF 1	

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